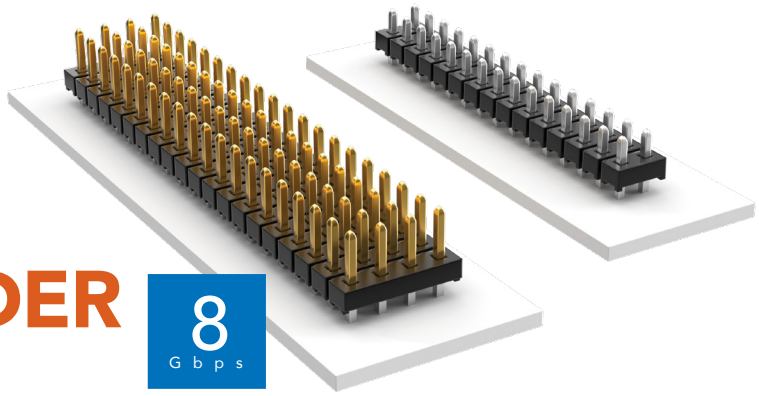


THROUGH-HOLE LOW PROFILE HEADER

8 Gbps

(2.00 mm) .0787" PITCH • TMM SERIES

TMM
Board Mates:
CLT, SQT, SQW, ESQT, TLE, SMM, MMS
Cable Mates:
TCSD

TMM	-	1	NO. PINS PER ROW	-	LEAD STYLE	-	PLATING OPTION	-	ROW OPTION	-	OTHER OPTION
			02 thru 50		Specify LEAD STYLE from chart		–F = Gold flash on post, Matte Tin on tail –L = 10 µ" (0.25 µm) Gold on post, Matte Tin on tail –T = Matte Tin		–S = Single Row –D = Double Row –Q = Four Row		–RA & –RE = Right-angle (Lead Style –01 only) (2 positions minimum, –Q row) –RC = Retention Clip (Mates with TCSD) (Double row only, 4 positions minimum, only available –06 lead style) –"XXX" = Polarized Position (Specify position of omitted pin)

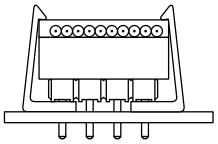
SPECIFICATIONS

Insulator Material:
Black Liquid Crystal Polymer
Terminal Material:
Phosphor Bronze
Plating:
Sn or Au over
50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +105 °C with Tin;
-55 °C to +125 °C with Gold
Current Rating (SMM/TMM):
3.3 A per pin
(2 pins powered)
Voltage Rating:
281 VAC/397 VDC
mated with SQW;
250 VAC/354 VDC
mated with SQT
375 VAC/530 VDC
mated with SMM

PROCESSING

Lead–Free Solderable:
Yes

APPLICATION



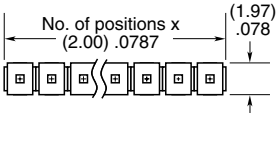
Retention Clip Option (–RC)

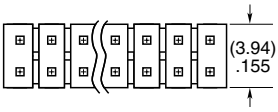
ALSO AVAILABLE
Contact Samtec

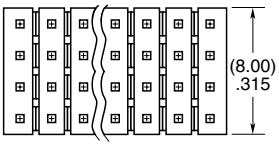
Other Platings

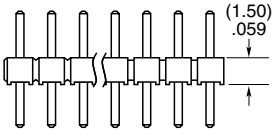
10 YEAR MFG WITH 30 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES

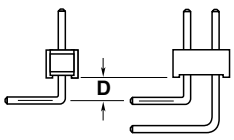
Note:
Some lengths, styles and options are non-standard, non-returnable.



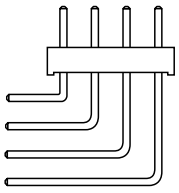




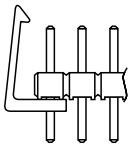




-RA & -RE

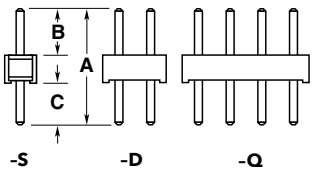


-Q -RA



-RC

OPTION	D
–RA	(1.27) .050
–RE	(3.56) .140



-S -D -Q

LEAD STYLE	A	B	C
–01	(8.20) .323	(3.20) .126	(3.50) .138
–02		(3.70) .146	(3.00) .118
–03		(4.00) .158	(2.70) .106
–04	(5.69) .224	(1.91) .075	(2.29) .090
–05	(5.43) .214	(1.65) .065	
–06	(9.58) .377	(3.20) .126	(4.88) .192

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.